

CSC THERMAL CONDUCTIVE PAD

TP-S3000 Series

Description & Applications

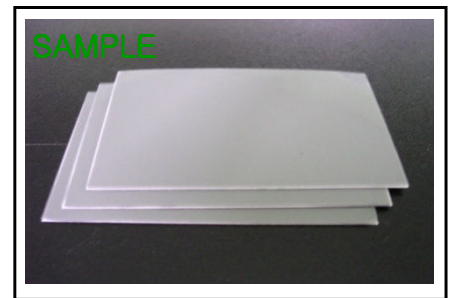
TP-S3000 has exceptionally low interfacial resistance to adjacent surfaces. Featuring a soft, very low hardness specially designed to comply to unique contours and topography and is ideal for fragile components.

- Memory Modules (DDR, S-RAM)
- Microprocessors
- BGA Packages



Main Features

- Thermal conductivity = 3.0 W/mK
- Self sticky properties
- Conformable low hardness
- Electrically insulating



Specifications

ITEM	TP-S3000	METHOD
Mechanical		
Color*	Light Gray	Visual
Thickness (mm)	0.1 ~ 5.0	ASTM D374
Density (g/cc)	2.7	ASTM D792
Hardness (Shore 00)	20	ASTM D2240
Tensile Strength (kgf/cm ²)	2	ASTM D412
Use Temp. (°C)	-60 ~ 200	-
Electrical		
Dielectric Breakdown Voltage (V)	> 6,000	ASTM D149
Volume Resistivity (Ω · cm)	10 ¹³	ASTM D257
Thermal		
Thermal Conductivity (W/mK)	3.0	ASTM C518-98 (Modified)
Flame Rating (UL94)	V-0	File No. E258204

※ Pad color can be adjustable upon request